What is claimed is:

1. A heat sink assembly adapted for attachment to an electronic component having an upper surface so as to dissipate heat generated from the electronic component comprising a heat sink and a clip, said clip having an upper wall and attachment means in turn for engaging portions of the electronic component for attachment thereto whereby said upper wall is spaced from the heat generating surface of the electronic component, said upper wall including an opening defined by a peripheral surface which in turn forms a collar, said heat sink including a lower base and an upper heat dissipating body, said base having a lower heat transfer surface adapted for contact with the upper surface of the electronic component and a reverse tapered working surface adapted to connectively contact said collar whereby said base and said heat sink may vertically move upwardly and downwardly with respect to said clip as the temperature of the electronic component is raised or lowered respectively.

2. The heat sink assembly of claim 1 wherein said heat sink base working surface is adapted to slide upwardly and downwardly while maintaining frictional contact with said collar.

3. The heat sink assembly of claim 2, wherein said heat sink base includes a connecting flange in turn defining a connection edge of a peripheral extent larger than said collar and wherein said connection edge is positioned above said lower heat transfer surface and said working surface.

4. The heat sink assembly of claim 3, wherein said base and said collar are both of circular configuration.

5. The heat sink assembly of claim 2, wherein said collar includes peripherally spaced outwardly flexible pressure cams in turn adapted for contact with said working surface.

6. The heat sink assembly of claim 2, wherein an upwardly outwardly tapered lower surface is positioned between said lower heat transfer surface and said working surface and wherein said tapered lower surface and said working surface connect along and cooperatively define said connection edge.

7. The heat sink assembly of claim 5, each of said pressure cams in part defined by a secondary opening positioned radially outwardly from said opening defining peripheral surface so as to define an outwardly flexible supporting material web, said webs forming said cams.

8. The heat sink assembly of claim 1, wherein said clip attachment means comprising downwardly extending flanges having an inwardly extending finger in turn adapted to extend beneath portions of the electronic component.